

Ther Putty S-3,5-2000

Patron
Passive Elektronik

Thermal Conductive Putty

Ther Putty S is a one-part dispensable material with thermal conductivity 3.5W/m*K. High deformation can fill small air gaps perfectly to remove tolerance. It also can overcome overflow and drying problems to increase the thermal conductivity. S-putty is a great alternative to thermal grease and ideally suited for dispensing using the dispensing robot.



FEATURES

- / Thermal conductivity: 3.5 W/m*K
- / Bond line thickness: 100-1500µm
- / Designed to remove manufacturing tolerances
- / Does not produce stress on delicate components
- / No vertical flow
- / Dispensable for serial manufacture
- / For any high compression and low stress application

TYPICAL APPLICATION

- / Between CPU and heat sink
- / Between a component and heat sink
- / High speed mass storage drives
- / Telecommunication hardware
- / Flat-panel displays
- / Set-top box

CONFIGURATIONS

- / Cartridges: 30ml, 55ml, 330ml
- / Bucket: 1kg, 25kg

PRESERVATION

It can be preserved for 60 months under the condition of unopened and under room temperature 25°C.

HOW TO ORDER

Patron THER PUTTY S-3,5-15000 XXX
XXX = packaging

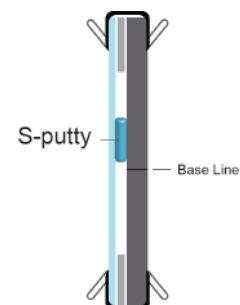
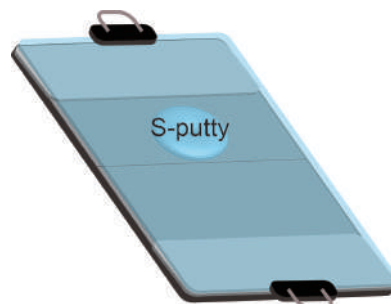
<https://www.patron-components.com/>

TYPICAL PROPERTIES

PROPERTY	PUTTY S	TEST METHOD	UNIT
Color	Blue	Visual	-
Resin base	Silicone	-	-
Viscosity	2000	DIN 53018	Pa.s
Density	3.0	ASTM D792	g/cm ³
Application temperature	-60~180	-	°C
Bond line thickness	100~1500	-	µm
Shelf life	60 months	-	-
ROHS & REACH	Compliant	-	-
ELECTRICAL			
Dielectric breakdown	12	ASTM D149	KV/mm
Volume resistivity	>10 ¹³	ASTM D257	Ohm-m
THERMAL			
Thermal conductivity	3.5	ASTM D5470	W/m*K
Thermal impedance@10psi	0.079	ASTM D5470	°C-in ² / W
Thermal impedance@30psi	0.071	ASTM D5470	°C-in ² / W
Thermal impedance@50psi	0.061	ASTM D5470	°C-in ² / W

VERTICAL RELIABILITY

Using 1.0mm pad as a gap control, put the putty between the aluminum and the glass panel mark the initial position. Then, place it in the oven with 125°C for 1,000 hours and observe its displacement after reliability test



Material no dropped or changed after high temperature aging testing